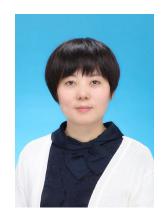
## Prof. Yuan Yang

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President of International Engineering College of XUT, Member of China Power Supply Society, Member of China Electro Technical Society, Member of Chinese Society of Academic Degrees and Graduate Education.



## **Education Background**

- BE, Applied Electronic Technology, Xi'an University of Technology, 1997.
- ME, Micro-Electronics and Solid Electronics, Xi'an University of Technology, 2000.
- Ph.D, Micro-Electronics and Solid Electronics, Xi'an University of Technology, 2004,
- Visiting Scholar, Kyushu University, 2004.

## **Research Field**

- Integrated Circuit Design
- Low Power Management
- Embedded System Design

## **Academic achievements**

- 1. Wei Yang, Wei Xiang, Yuan Yang, Peng Cheng, Optimizing federated learning with deep reinforcement learning for digital twin empowered industrial IoT. IEEE Transactions on Industrial Informatics, vol.19(2), pp. 1884-1893, 2023.
- 2. Yuan Yang, Yang Wen, Yong Gao. A novel active gate driver for improving switching performance of high-power SiC MOSFET modules. IEEE Transactions on Power Electronics, vol. 34(8), pp. 7775-7787, 2019.
- 3. Yang Wen, Yuan Yang, Yong Gao. Active gate driver for improving current sharing performance of paralleled high-power SiC MOSFET modules. IEEE Transactions on Power Electronics, vol. 36(2), pp. 1491-1505, 2021.
- 4. Fengjuan Wang, Kai Zhang, Xiangkun Yin, Ningmei Yu, Yuan Yang. A miniaturized wideband interdigital bandpass filter with high out-band suppression based on TSV technology for W-band application. IEEE Transactions on Very Large Scale Integration Systems. Vol. 30(7), pp. 989-992, 2022.
- 5. Tong Zhang, Lisha Yan, Yuan Yang, Trust Evaluation Method for Clustered Wireless Sensor Networks based on Cloud Model, Wireless Networks, Vol.24, No.3, pp.777-797, 2018.
- 6. Haohao Ma, Yuan Yang, Lei Wu, Yang Wen, Qiang Li. Review of the designs in low inductance SiC half-bridge packaging. IET Power Electronics, vol. 15(11), pp. 989-1003, 2022.